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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re application of: Wang et al.

Attorney Docket No.: ALTRP100/A1198

Application No.: 10/719,218

Examiner: RAO, Shrinivas H.

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL AND DESIGN FOR ASSEMBLING A LOW-K Si DIE TO ACHIEVE AN INDUSTRIAL GRADE RELIABILITY WIRE BONDING PACKAGE Confirmation No.: 3208

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**CERTIFICATE OF EFS-WEB TRANSMISSION**

I hereby certify that this correspondence is being transmitted electronically through EFS-WEB to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450 on August 29, 2007.

Signed: /Laura M. Dean/  
Laura M. Dean

**AMENDMENT E**  
**FILED CONCURRENTLY WITH RCE**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the final Office Action mailed May 29, 2007, please consider the following remarks and amend the above-identified application as follows.

**Amendments to the Claims** are reflected in the listing of claims, which begin on page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.